



FINAL PRODUCT/PROCESS CHANGE NOTIFICATIONGeneric Copy

15 Jun 2007**SUBJECT: ON Semiconductor Final Product/Process Change Notification #16018****TITLE: Final PCN for Qualification of UDFN Packages in ON Semiconductor Seremban****PROPOSED FIRST SHIP DATE: 15 Aug 2007****AFFECTED CHANGE CATEGORY(S): ON Semiconductor Assembly Site****AFFECTED PRODUCT DIVISION(S): Digital Consumer Group****FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Angela Tam <Angela.Tam@onsemi.com>**SAMPLES:** Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Rick Luevanos <r.luevanos@onsemi.com>**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 60 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:This is a Final PCN (Product Change Notice) to notify customers that the changes described in PCN#15676 have been completed for the listed devices. The Initial PCN can be found at www.onsemi.com.

ON Semiconductor is pleased to announce that the following packages are qualified to be assembled in ON Semiconductor, Seremban, Malaysia. The qualified packages are UDFN16 3.5 x 1.2 mm, UDFN12 2.5 x 1.2 mm, and UDFN8 1.8 x 1.2 mm. The devices listed under the "Affected Device List" can be assembled in ON Semiconductor facility in Seremban, Malaysia or the current qualified assembly site, UTAC (located in Bangkok, Thailand) upon the expiration of the FPCN.

There will be no changes in device functionality, case outline, or footprint. Reliability will continue to meet or exceed ON Semiconductor's highest standards.

Any new devices or derivatives package from same DFN/QFN platform released after the expiration of this FPCN will be qualified for assembly in both UTAC and ON Semiconductor, Seremban.

**Final Product/Process Change Notification #16018****RELIABILITY DATA SUMMARY:****Reliability Test Results:**

Test	Conditions	Results
Temperature Cycling - MSL1 Preconditioning	Ta = 65/150 deg C, air to air, 1000 cycles	0 reject / 77 units; 0 reject / 77 units; 0 reject / 77 units
Autoclave – MSL 1 Preconditioning	121 deg C/100% RH/ 15 psig; 96 hrs	0 reject / 76 units; 0 reject / 77 units; 0 reject / 76 units
Highly Accelerated Stress Test – MSL1 Preconditioning	Temp = 130 deg C, RH = 85% for 96 hrs	0 reject / 77 units; 0 reject / 77 units; 0 reject / 77 units
Resistance to Solder Heat	Ta = 260 deg C	0 reject / 35 units
Solderability	Ta = 245 deg C	0 reject / 20 units

ELECTRICAL CHARACTERISTIC SUMMARY:

All products' performance meets current datasheet specifications.

CHANGED PART IDENTIFICATION:

Products manufactured after the FPCN expiration date can be manufactured at either UTAC or ON Semiconductor Seremban location. Assembly location code will be maintained for traceability.

AFFECTED DEVICE LIST

NUF2450MUT2G
NUF4001MUT2G
NUF6001MUT2G
NUF8001MUT2G